



2831

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Tan, Aik Chong et al.  
Serial No.: 09/736,462  
Filing Date: December 15, 2000  
Group Art Unit: 2831  
Examiner: Hung V. Ngo  
Title: BUMP CHIP LEADFRAME AND PACKAGE

TECHNICAL UNIT 2800

#3  
OP  
11/8/01  
Election

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH  
THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL IN AN  
ENVELOPE ADDRESSED TO:

COMMISSIONER OF PATENTS AND TRADEMARKS

WASHINGTON, D.C. 20231, ON:

OCTOBER 31, 2001

Date of Deposit

SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

Name of Assignee

*Lydia Mchamara*

SIGNATURE

10/31/01

DATE

Honorable Commissioner of Patents and Trademarks,  
Washington, D.C. 20231

SIR:

ELECTION

In response to the Office Action mailed October 19, 2001,  
Applicants respectfully request the election of the Group I  
claims, which include claims 1-9 pursuant to 37 CFR 1.142(a)  
without traverse. Group II include claims 10-16, which are  
drawn to a lead frame, classified in class 257, subclass 666.